

## General Description

The MY20N06F uses advanced trench technology and design to provide excellent RDS(ON) with low gate Charge. It can be used in a wide variety of applications.

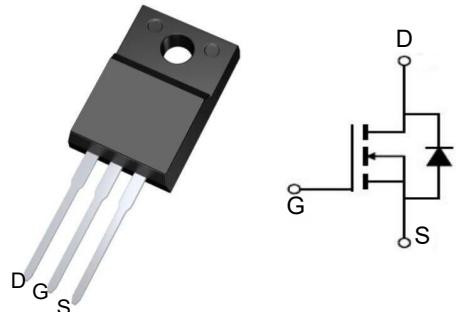


## Features

V <sub>DSS</sub>	60	V
I <sub>D</sub>	20	A
R <sub>DSON</sub> (at V <sub>GS</sub> = 10V)	30	mΩ
R <sub>DSON</sub> (at V <sub>GS</sub> = 4.5V)	38	mΩ

## Application

- Power switching application.
- Hard switched and high frequency circuits.
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty( PCS)
MY20N06F	TO-220F	MY20N06F	1000

## Absolute Maximum Ratings ( T<sub>C</sub>= 25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain- Source Voltage	60	V
V <sub>GS</sub>	Gate Source Voltage	±20	V
I <sub>D</sub> @ T <sub>C</sub> =25 °C	Continuous Drain Current <sup>1</sup>	20	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current <sup>1</sup>	13	A
I <sub>DM</sub>	Pulsed Drain Current <sup>3</sup>	80	A
E <sub>AS,EAR</sub>	Avalanche Energy <sup>5</sup>	7	mJ
I <sub>AS,IAR</sub>	Avalanche Current <sup>5</sup>	12	A
P <sub>D</sub> @ T <sub>C</sub> =25 °C	Total Power Dissipation <sup>4</sup>	29	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJC</sub>	Thermal Resistance, Junction- to- Case <sup>2</sup>	4.7	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>2</sup>	62	°C/W

**Electrical Characteristics (T<sub>c</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =100uA	60	---	---	V
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	---	30	36	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	38	43	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1	2	3	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =10A	---	7	---	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	16.6	24	nC
Q <sub>gs</sub>	Gate-Source Charge		---	2.2	4.4	
Q <sub>gd</sub>	Gate-Drain Charge		---	3.9	8	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, I <sub>DS</sub> =1A , V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω	---	4.8	9	nS
T <sub>r</sub>	Rise Time		---	14.5	28	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	27	52	
T <sub>f</sub>	Fall Time		---	7.5	15	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	---	882	1460	pF
C <sub>oss</sub>	Output Capacitance		---	58	90	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	35	70	

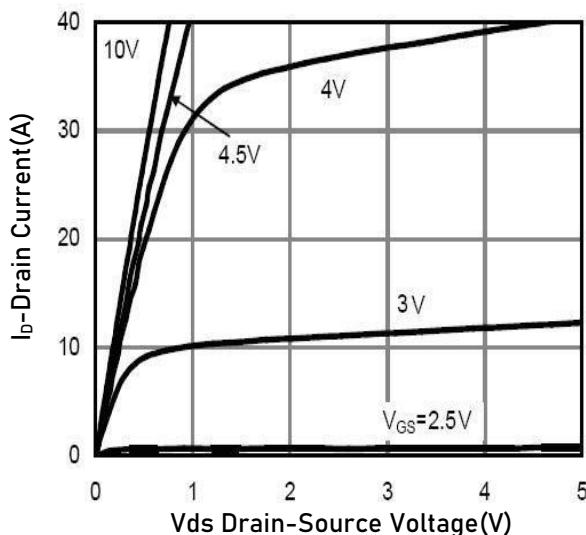
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current <sup>1,4</sup>	VG=VD=0V	---	---	20	A
I <sub>SM</sub>	Pulsed Source Current		---	---	80	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>SD</sub> =10A, T <sub>J</sub> =25°C	---	---	0.8	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>s</sub> =1A, V <sub>GS</sub> =0V, di/dt=100A/μs T <sub>J</sub> =25°C	---	17	---	nS
			---	12	---	nC

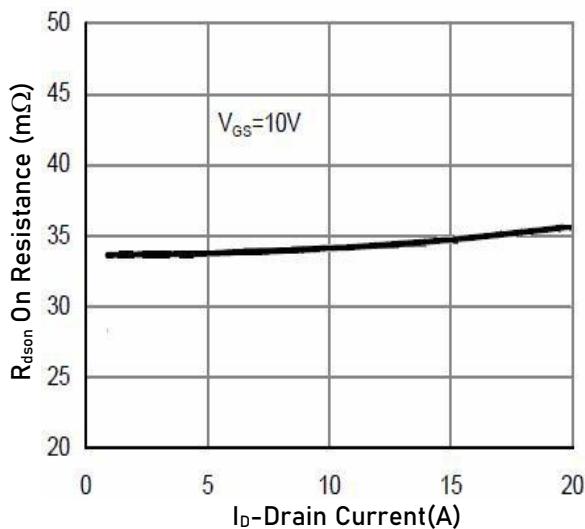
**Notes:**

- 1 . Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2 . Surface Mounted on FR4 Board, t ≤ 1 0 sec.
- 3 . Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤2 %.
- 4 . The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.
- 5 . The EAS test condition is V<sub>DD</sub> =30V,V<sub>GS</sub> =10V,L=0.1mH,I<sub>AS</sub> =12A

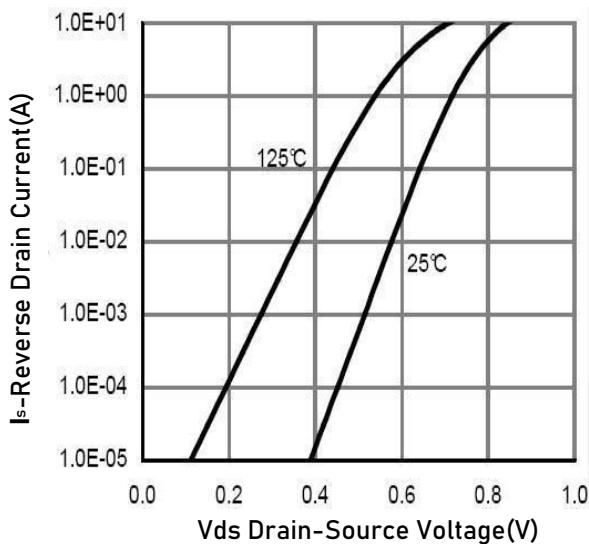
**Ratings and Characteristic curves**



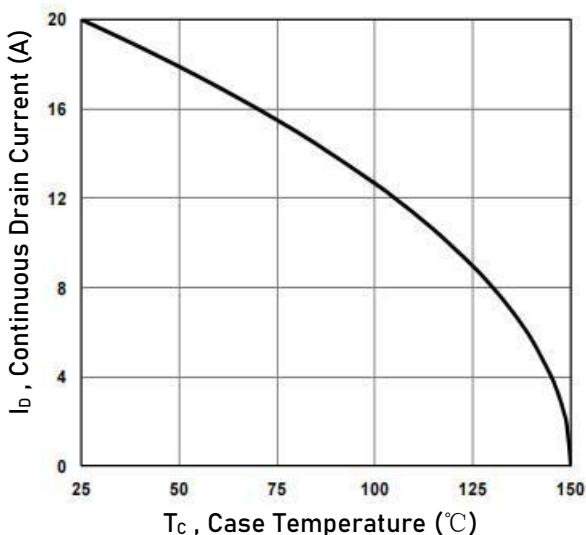
**Fig.1 Typical Output Characteristics**



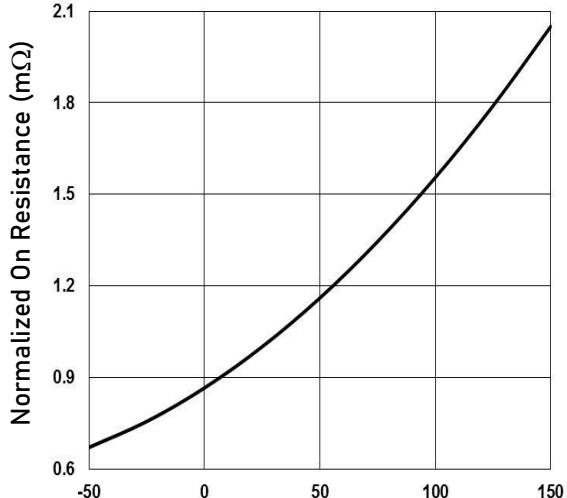
**Fig.3 Drain-Source On Resistance**



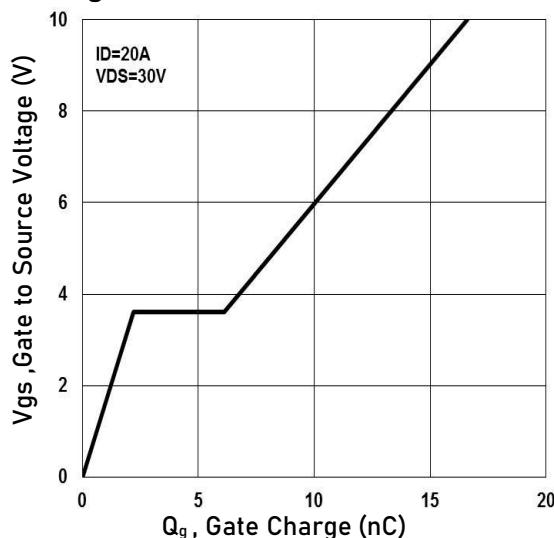
**Fig.5 Forward Characteristics Of Reverse**



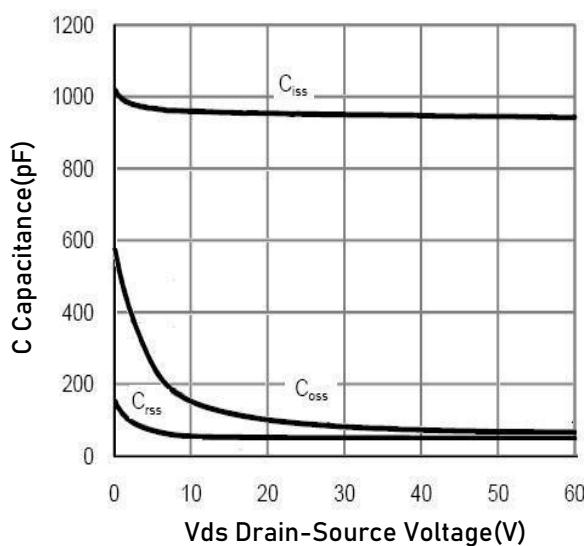
**Fig.2 Drain Current**



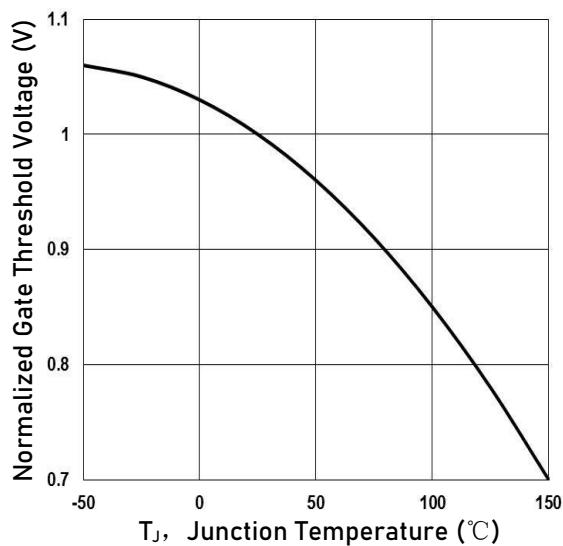
**Fig.4 Normalized RDSON vs.  $T_j$**



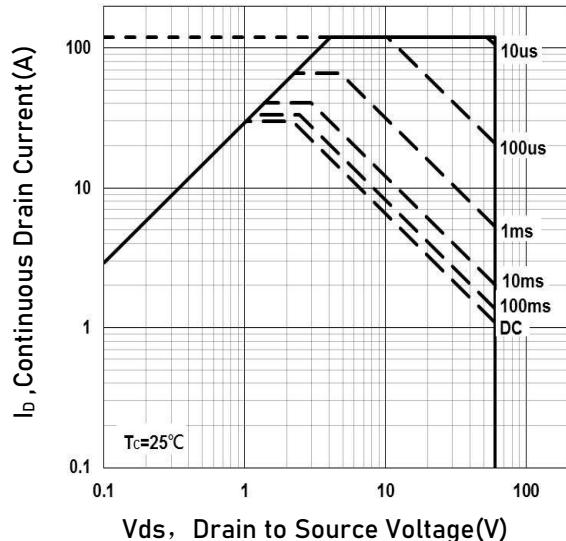
**Fig.6 Gate-Charge Characteristics**



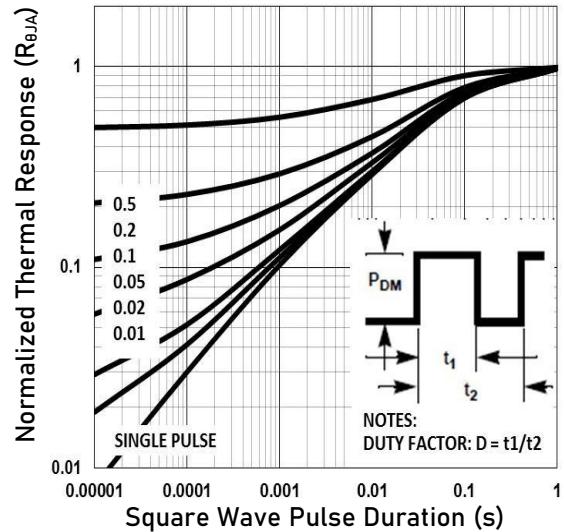
**Fig.7 Capacitance**



**Fig.8 Normalized  $V_{th}$  vs.  $T_J$**

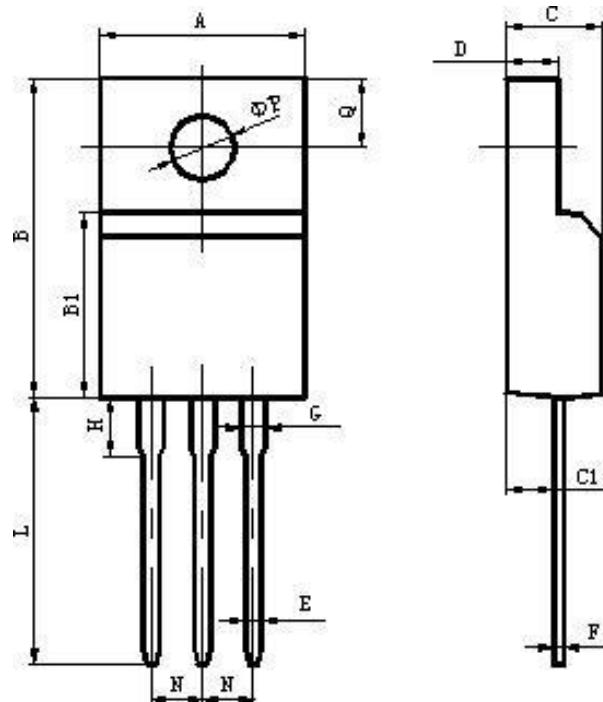


**Fig.9 Safe Operating Area**



**Fig.10 Transient Thermal Impedance**

**Package Mechanical Data-TO-220F Single**



Items	Values(mm)	
	MIN	MAX
A	9.60	10.4
B	15.4	16.2
B1	8.90	9.50
C	4.30	4.90
C1	2.10	3.00
D	2.40	3.00
E	0.60	1.00
F	0.30	0.60
G	1.12	1.42
H	3.40	3.80
	2.40	2.90
L*	12.0	14.0
N	2.34	2.74
Q	3.15	3.55
Φ P	2.90	3.30